## Product Specification

## PE42821

## UltraCMOS ${ }^{\circledR}$ SPDT RF Switch 100-2700 MHz

## Features

- High power handling
- $45 \mathrm{dBm} @ 850 \mathrm{MHz}, 32 \mathrm{~W}$
- 44 dBm @ 2 GHz, 25W
- High linearity
- 82 dBm IIP3 @ 850 MHz
- 76 dBm IIP3 @ 2.7 GHz
- Low insertion loss
- 0.35 dB @ 850 MHz
- 0.60 dB @ 2 GHz
- Fast switching time of $4 \mu \mathrm{~s}$ (bypass mode)
- Wide supply range of $2.3-5.5 \mathrm{~V}$
- +1.8 V control logic compatible
- ESD performance
- 1.5 kV HBM on all pins
- External negative supply option

Figure 2. Package Type
32-lead $5 \times 5 \mathrm{~mm}$ QFN


Table 1. Electrical Specifications $@+25^{\circ} \mathrm{C}\left(Z_{S}=Z_{L}=50 \Omega\right)$, unless otherwise noted Normal mode ${ }^{1}$ : $\mathrm{V}_{\mathrm{DD}}=3.3 \mathrm{~V}, \mathrm{~V}_{\text {SS_EXT }}=0 \mathrm{~V}$ or Bypass mode ${ }^{2}$ : $\mathrm{V}_{\mathrm{DD}}=3.3 \mathrm{~V}, \mathrm{~V}_{\mathrm{SS} \text { _EXT }}=-3.3 \mathrm{~V}$

| Parameter | Path | Condition | Min | Typ | Max | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Insertion loss ${ }^{3}$ | RFC-RFX | $\begin{aligned} & 100 \mathrm{MHz}-1 \mathrm{GHz} \\ & 1-2 \mathrm{GHz} \\ & 2-2.7 \mathrm{GHz} \end{aligned}$ |  | $\begin{aligned} & 0.40 \\ & 0.60 \\ & 0.80 \end{aligned}$ | $\begin{aligned} & 0.55 \\ & 0.80 \\ & 1.05 \end{aligned}$ | dB <br> dB <br> dB |
| Isolation | RFX-RFX | $\begin{aligned} & 100 \mathrm{MHz}-1 \mathrm{GHz} \\ & 1-2 \mathrm{GHz} \\ & 2-2.7 \mathrm{GHz} \end{aligned}$ | $\begin{aligned} & 33 \\ & 26 \\ & 22 \end{aligned}$ | $\begin{aligned} & 35 \\ & 28 \\ & 24 \end{aligned}$ |  | dB <br> dB <br> dB |
| Unbiased isolation | RFC-RFX | $\mathrm{V}_{\mathrm{DD}}, \mathrm{V} 1=0 \mathrm{~V},+27 \mathrm{dBm}$ |  | 6 |  | dB |
| Return loss ${ }^{3}$ | RFX | $\begin{aligned} & 100 \mathrm{MHz}-1 \mathrm{GHz} \\ & 1-2 \mathrm{GHz} \\ & 2-2.7 \mathrm{GHz} \end{aligned}$ |  | $\begin{aligned} & 20 \\ & 13 \\ & 14 \end{aligned}$ |  | dB <br> dB <br> dB |
| Harmonics | RFC-RFX | 2fo: +45 dBm pulsed @ 1GHz, 50 <br> 3fo: +45 dBm pulsed @ 1GHz, $50 \Omega$ |  | $\begin{aligned} & \hline-82 \\ & -85 \end{aligned}$ | $\begin{aligned} & \hline-78 \\ & -81 \end{aligned}$ | dBc <br> dBc |
| Input IP3 | RFC-RFX | $\begin{aligned} & 850 \mathrm{MHz} \\ & 2700 \mathrm{MHz} \end{aligned}$ |  | $\begin{aligned} & 82 \\ & 76 \end{aligned}$ |  | $\begin{aligned} & \mathrm{dBm} \\ & \mathrm{dBm} \end{aligned}$ |
| Input 0.1 dB compression point ${ }^{4}$ | RFC-RFX | $\begin{aligned} & 100 \mathrm{MHz}-2 \mathrm{GHz} \\ & 2-2.7 \mathrm{GHz} \end{aligned}$ |  | $\begin{aligned} & 45.5 \\ & 44.5 \end{aligned}$ |  | dBm <br> dBm |
| Switching time in normal mode ${ }^{1}$ |  | $50 \%$ CTRL to $90 \%$ or $10 \%$ RF |  | 7 | 11 | $\mu \mathrm{s}$ |
| Switching time in bypass mode ${ }^{2}$ |  | $50 \%$ CTRL to $90 \%$ or 10\% RF |  | 4 |  | $\mu \mathrm{s}$ |
| Settling time |  | $50 \%$ CTRL to harmonics within specifications ${ }^{5}$ |  | 15 | 25 | $\mu \mathrm{s}$ |

Notes: 1. Normal mode: single external positive supply used.
2. Bypass mode: both external positive supply and external negative supply used.
3. Performance specified with external matching. Refer to Evaluation Kit section for additional information.
4. The input 0.1 dB compression point is a linearity figure of merit. Refer to Table 3 for the operating RF input power ( $50 \Omega$ ).
5. See harmonics specs above.

Figure 3. Pin Configuration (Top View)


Table 2. Pin Descriptions

| Pin \# | Pin Name | Description |
| :---: | :---: | :--- |
| $1,3-11$, <br> $14,15,17-$ <br> $22,24-27$, <br> $29-32$ | GND | Ground |
| 2 | RF1 $^{1}$ | RF port |
| 12 | V $_{\text {DD }}$ | Supply voltage (nominal 3.3V) |
| 13 | V1 $^{1}$ | Digital control logic input 1 |
| 16 | V $_{\text {Ss_Ex }}{ }^{2}$ | External $\mathrm{V}_{\text {SS }}$ negative voltage control |
| 23 | RF2 $^{1}$ | RF port |
| 28 | RFC $^{1}$ | RF common |
| Pad | GND | Exposed pad: ground for proper operation |

Notes: 1. RF pins 2,23 and 28 must be at 0 VDC. The RF pins do not require DC blocking capacitors for proper operation if the 0 VDC requirement is met.
2. Use $\mathrm{V}_{\text {SS_EXT }}\left(\operatorname{pin} 16, \mathrm{~V}_{\text {SS_EXT }}=-\mathrm{V}_{\mathrm{DD}}\right.$ ) to bypass and disable internal negative voltage generator. Connect $\mathrm{V}_{\text {SS_EXT }}$ (pin 16, $\mathrm{V}_{\text {SS_EXT }}=\mathrm{GND}$ ) to enable internal negative voltage generator.

Table 3. Operating Ranges

| Parameter | Symbol | Min | Typ | Max | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: |
| Normal mode ${ }^{1}$ |  |  |  |  |  |
| Supply voltage | $V_{D D}$ | 2.3 |  | 5.5 | V |
| Supply current | $I_{\text {DD }}$ |  | 130 | 200 | $\mu \mathrm{A}$ |
| Bypass mode ${ }^{2}$ |  |  |  |  |  |
| Supply voltage | $V_{\text {DD }}$ |  | 3.3 | 5.5 | V |
| Supply current | IDD |  | 50 | 80 | $\mu \mathrm{A}$ |
| Negative supply voltage | $\mathrm{V}_{\text {SS_EXT }}$ | -3.6 |  | -3.2 | V |
| Negative supply current | $I_{\text {ss }}$ | -40 | -16 |  | $\mu \mathrm{A}$ |
| Normal or Bypass mode |  |  |  |  |  |
| Digital input high (V1) | $\mathrm{V}_{\mathrm{IH}}$ | 1.17 |  | $3.6{ }^{3}$ | V |
| Digital input low (V1) | $\mathrm{V}_{\text {IL }}$ | $-0.3$ |  | 0.6 | V |
| $\begin{gathered} \text { RF input power, CW } \\ 100 \mathrm{MHz}-2 \mathrm{GHz} \\ >2-2.7 \mathrm{GHz} \end{gathered}$ | $\mathrm{P}_{\text {MAX,CW }}$ |  |  | $\begin{aligned} & 43 \\ & 42 \end{aligned}$ | dBm dBm |
| $\begin{aligned} & \text { RF input power, } \\ & \text { pulsed } \\ & \quad 100 \mathrm{MHz}-2 \mathrm{GHz} \\ & >2-2.7 \mathrm{GHz} \end{aligned}$ | $\mathrm{P}_{\text {MAX, PULSEd }}$ |  |  | $\begin{aligned} & 45 \\ & 44 \end{aligned}$ | dBm dBm |
| RF input power, unbiased | $\mathrm{P}_{\text {max, unb }}$ |  |  | 27 | dBm |
| Operating temperature range (Case) | Top | -40 |  | +85 | ${ }^{\circ} \mathrm{C}$ |
| Operating junction temperature | TJ |  |  | +140 | ${ }^{\circ} \mathrm{C}$ |

Notes: 1. Normal mode: connect pin 16 to GND to enable internal negative voltage generator.
2. Bypass mode: apply a negative voltage to $\mathrm{V}_{\text {Ss_Ext }}$ (pin 16) to bypass and disable internal negative voltage generator.
3. Maximum $\mathrm{V}_{\mathbb{H}}$ voltage is limited to $\mathrm{V}_{\mathrm{DD}}$ and cannot exceed 3.6 V .
4. Pulsed, $10 \%$ duty cycle of $4620 \mu \mathrm{~s}$ period, $50 \Omega$.

Table 4. Absolute Maximum Ratings

| Parameter/Condition | Symbol | Min | Max | Unit |
| :--- | :---: | :---: | :---: | :---: |
| Supply voltage | $\mathrm{V}_{\mathrm{DD}}$ | -0.3 | 5.5 | V |
| Digital input voltage (V1) | $\mathrm{V}_{\mathrm{CTRL}}$ | -0.3 | 3.6 | V |
| Maximum input power <br> $100 \mathrm{MHz-2} \mathrm{GHz}$ <br> $>2-2.7 \mathrm{GHz}$ | $\mathrm{P}_{\mathrm{MAX}, \mathrm{ABS}}$ |  | 45.5 | dBm |
| dBm |  |  |  |  |
| Storage temperature range | $\mathrm{T}_{\mathrm{ST}}$ | -65 | +150 | ${ }^{\circ} \mathrm{C}$ |
| Maximum case temperature | $\mathrm{T}_{\mathrm{CASE}}$ |  | +85 | ${ }^{\circ} \mathrm{C}$ |
| Peak maximum junction <br> temperature (10 seconds max) | $\mathrm{T}_{\mathrm{J}}$ |  | +200 | ${ }^{\circ} \mathrm{C}$ |
| ESD voltage $\mathrm{HBM}^{1}$, all pins | $\mathrm{V}_{\mathrm{ESD}, \mathrm{HBM}}$ |  | 1500 | V |
| ESD voltage $\mathrm{MM}^{2}$, all pins | $\mathrm{V}_{\mathrm{ESD}, \mathrm{MM}}$ |  | 200 | V |
| ESD voltage $\mathrm{CDM}^{3}$, all pins | $\mathrm{V}_{\mathrm{ESD}, \mathrm{CDM}}$ |  | 250 | V |

Notes: 1. Human Body Model (MIL-STD 883 Method 3015)
2. Machine Model (JEDEC JESD22-A115)
3. Charged Device Model (JEDEC JESD22-C101)

Exceeding absolute maximum ratings may cause permanent damage. Operation should be restricted to the limits in the Operating Ranges table. Operation between operating range maximum and absolute maximum for extended periods may reduce reliability.

## Electrostatic Discharge (ESD) Precautions

When handling this UltraCMOS device, observe the same precautions that you would use with other ESD-sensitive devices. Although this device contains circuitry to protect it from damage due to ESD, precautions should be taken to avoid exceeding the rating specified.

## Latch-Up Avoidance

Unlike conventional CMOS devices, UltraCMOS devices are immune to latch-up.

## Moisture Sensitivity Level

The Moisture Sensitivity Level rating for the 32lead $5 \times 5 \mathrm{~mm}$ QFN package is MSL3.

Table 5. Control Logic Truth Table

| Path | CTRL |
| :---: | :---: |
| RFC-RF1 | H |
| RFC-RF2 | L |

## Optional External $\mathbf{V}_{\text {SS }}$ Control ( $\mathbf{V}_{\text {SS_ExT }}$ )

For applications that require a faster switching rate or spur-free performance, this part can be operated in bypass mode. Bypass mode requires an external negative voltage in addition to an external $\mathrm{V}_{\mathrm{DD}}$ supply voltage.

As specified in Table 3, the external negative voltage ( $\mathrm{V}_{\text {SS_ExT }}$ ) when applied to pin 16 will disable and bypass the internal negative voltage generator.

## Switching Frequency

The PE42821 has a maximum 25 kHz switching rate in normal mode (pin 16 = GND). A faster switching rate is available in bypass mode (pin 16 $=\mathrm{V}_{\text {SS_EXT }}$ ). The rate at which the PE42821 can be switched is then limited to the switching time as specified in Table 1.

Switching frequency describes the time duration between switching events. Switching time is the time duration between the point the control signal reaches $50 \%$ of the final value and the point the output signal reaches within $10 \%$ or $90 \%$ of its target value.

## Spurious Performance

The typical low-frequency spurious performance of the PE42821 in normal mode is -137 dBm (pin $16=$ GND). If spur-free performance is desired, the internal negative voltage generator can be disabled by applying a negative voltage to $\mathrm{V}_{\text {SS_EXT }}$ (pin 16).

## Hot Switching Capability

The typical hot switching capability of the PE42821 is +30 dBm . Hot switching occurs when RF power is applied while switching between RF ports.

Typical Performance Data $@+25^{\circ} \mathrm{C}, \mathrm{V}_{\mathrm{DD}}=3.3 \mathrm{~V}, \mathrm{~V}_{\text {SS_ExT }}=0 \mathrm{~V}$, unless otherwise noted

Figure 4. Insertion Loss vs. Temp (RFC-RFX)


Figure 6. RFC Port Return Loss vs. Temp (RF1 Active)


Figure 5. Insertion Loss vs. VDD (RFC-RFX)


Figure 7. RFC Port Return Loss vs. $\mathrm{V}_{\mathrm{DD}}$ (RF1 Active)


## Typical Performance Data @ +25 ${ }^{\circ} \mathrm{C}, \mathrm{V}_{\mathrm{DD}}=3.3 \mathrm{~V}, \mathrm{~V}_{\text {Ss Ext }}=0 \mathrm{~V}$, unless otherwise noted

Figure 8. Active Port Return Loss vs. Temp (RF1 Active)


Figure 10. Isolation vs. Temp
(RFC-RFX, RFX Active)


Figure 9. Active Port Return Loss vs. $\mathrm{V}_{\mathrm{DD}}$ (RF1 Active)


Figure 11. Isolation vs. $\mathrm{V}_{\mathrm{DD}}$
(RFC-RFX, RFX Active)


Typical Performance Data $@+25^{\circ} \mathrm{C}, \mathrm{V}_{\mathrm{DD}}=3.3 \mathrm{~V}, \mathrm{~V}_{\text {SS_ExT }}=0 \mathrm{~V}$, unless otherwise noted

Figure 12. Isolation vs. Temp (RFX-RFX, RFX Active)


Figure 13. Isolation vs. $V_{D D}$
(RFX-RFX, RFX Active)


## Thermal Data

Though the insertion loss for this part is very low, when handling high power RF signals, the junction temperature rises significantly.

VSWR conditions that present short circuit loads to the part can cause significantly more power dissipation than with proper matching.

Special consideration needs to be made in the design of the PCB to properly dissipate the heat away from the part and maintain the $85^{\circ} \mathrm{C}$ maximum case temperature. It is recommended to use best design practices for high power QFN packages: multi-layer PCBs with thermal vias in a thermal pad soldered to the slug of the package. Special care also needs to be made to alleviate solder voiding under the part.

Table 6. Theta JC

| Parameter | Min | Typ | Max | Unit |
| :---: | :---: | :---: | :---: | :---: |
| Theta JC $\left(+85^{\circ} \mathrm{C}\right)$ |  | 20 |  | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |

## Evaluation Kit

The PE42821 Evaluation Kit board was designed to ease customer evaluation of the PE42821 RF switch.

The evaluation board in Figure 14 was designed to test the part. DC power is supplied through J10, with VDD on pin 9, and GND on the entire lower row of even numbered pins. To evaluate a switch path, add or remove jumpers on V1 (pin 3) using Table 5.

The ANT port is connected through a $50 \Omega$ transmission line via the top SMA connector, J1. RF1 and RF2 paths are also connected through $50 \Omega$ transmission lines via SMA connectors as J2 and J3. A $50 \Omega$ through transmission line is available via SMA connectors J5 and J6. This transmission line can be used to estimate the loss of the PCB over the environmental conditions being evaluated. An open-ended $50 \Omega$ transmission line is also provided at J 4 for calibration if needed.

Narrow trace widths are used near each part to improve impedance matching. The shunt C1 on RFC port is to provide for high frequency impedance matching.

Figure 14. Evaluation Board Layout


PE42821

Figure 15. Evaluation Board Schematic


Figure 16. Package Drawing 32-lead 5x5 mm QFN


Figure 17. Top Marking Specification


17-0085

Figure 18. Tape and Reel Specs


Table 7. Ordering Information

| Order Code | Description | Package | Shipping Method |
| :---: | :---: | :---: | :---: |
| PE42821MLBA-X | PE42821 SPDT RF switch | Green 32-lead $5 \times 5 \mathrm{~mm}$ QFN | 500 units/T\&R |
| EK42821-02 | PE42821 Evaluation kit | Evaluation kit | $1 / B o x$ |

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